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IRF710-713 MTP2N35/2N40 N-Channel Power MOSFETs, 2.25 A, 350-400 V Power And Discrete Division

These devices are n-channel, enhancement mode, power MOSFETs designed especially for high speed applications, such as switching power supplies, converters, AC and DC motor controls, relay and solenoid driver and high energy pulse circuits.

- Low R_{DS(on)}
- V_{GS} Rated at ± 20 V
- · Silicon Gate for Fast Switching Speeds
- I_{DSS}, V_{DS(on)}, Specified at Elevated Temperature Rugged
- Low Drive Requirements
- Ease of Paralleling

Maximum Ratings

TO-220AB



IRF710 **IRF711** IRF712 **IRF713** MTP2N35 MTP2N40

Symbol	Characteristic	Rating IRF710/712 MTP2N40	Rating IRF711/713 MTP2N35	Unit	
V _{DSS}	Drain to Source Voltage ¹ 400		350	٧	
V _{DGR}	Drain to Gate Voltage ¹ 400 $R_{GS} = 20 \text{ k}\Omega$		350 V		
V _{GS}	Gate to Source Voltage	± 20	± 20	V	
T _J , T _{stg}	Operating Junction and Storage Temperatures	-55 to +150	-55 to +150	°C	
TL	Maximum Lead Temperature for Soldering Purposes, 1/8" From Case for 5 s	275	275	°C	

Maximum On-State Characteristics

		IRF710-711	IRF712-713	MTP2N35/40	Unit
R _{DS(on)}	Static Drain-to-Source On Resistance	3.6	5.0	5.0	Ω
I _D	Drain Current Continuous at T _C = 25°C Continuous at T _C = 100°C Pulsed	1.5 1.0 6.0	1.4 0.9 5.0	1.3 0.8 5.0	A
Maximum	Thermal Characteristics				
$R_{\theta JC}$	Thermal Resistance, Junction to Case	6.4	6.4	2.5	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	80	80	80	°C/W
P _D	Total Power Dissipation at T _C = 25°C	20	20	50	. W

NJ Semi-Conductors reserves the right to change test conditions, parameter limits and package dimensions without notice. Information furnished by NJ Semi-Conductors is believed to be both accurate and reliable at the time of going to press. However, NJ Semi-Conductors assumes no responsibility for any errors or omissions discovered in its use. NJ Semi-Conductors encourages customers to verify that datasheets are current before placing orders.



IRF710-713 MTP2N35/2N40

Symbol	Characteristic	Min	Max	Unit	Test Conditions	
Off Charac	teristics					
V _{(BR)DSS}	Drain Source Breakdown Voltage ¹			V	$V_{GS} = 0 \text{ V, } I_D = 250 \mu\text{A}$	
	IRF710/712/MTP2N40	400				
	IRF711/713/MTP2N35	350				
IDSS	Zero Gate Voltage Drain Current		250	μΑ	V _{DS} = Rated V _{DSS} , V _{GS} = 0 V	
			1000	μΑ	$V_{DS} = 0.8 \times \text{Rated } V_{DSS},$ $V_{GS} = 0 \text{ V}, T_C = 125^{\circ}\text{C}$	
I _{GSS}	Gate-Body Leakage Current		± 500	nA	V _{GS} = ± 20 V, V _{DS} = 0 V	
On Charac	teristics					
V _{GS(th)}	Gate Threshold Voltage			V		
	IRF710-713	2.0	4.0		$I_D = 250 \mu A, V_{DS} = V_{GS}$	
	MTP2N35/2N40	2.0	4.5		$I_D = 1$ mA, $V_{DS} = V_{GS}$	
R _{DS(on)}	Static Drain-Source On-Resistance ²			Ω	V _{GS} = 10 V, I _D = 0.8 A	
	IRF710/711		3.6			
	IRF712/713/MTP2N35/40		5.0			
V _{DS(on)}	Drain-Source On-Voltage ²		13	V	V _{GS} = 10 V, I _D = 2.0 A	
	MTP2N35/2N40		10	V	V _{GS} = 10 V, I _D = 1.0 A, T _C = 100°C	
9fs	Forward Transconductance	0.5		s (හ)	V _{DS} = 10 V, I _D = 0.8 A	
Dynamic C	haracteristics					
Ciss	Input Capacitance		200	ρF	V _{DS} = 25 V, V _{GS} = 0 V	
Coss	Output Capacitance		50	pF	f = 1.0 MHz	
C _{rss}	Reverse Transfer Capacitance		15	pF		
Switching (Characteristics (T _C = 25°C, Figures 11,	12) ³				
t _{d(on)}	Turn-On Delay Time		10	ns	V _{DD} = 200 V, I _D = 0.8 A	
t _r	Rise Time		20	ns	$V_{GS} = 10 \text{ V}, R_{GEN} = 50 \Omega$ $R_{GS} = 50 \Omega$	
· t _{d(off)}	Turn-Off Delay Time		10	ns		
t _f	Fall Time		15	ns	1	
Qg	Total Gate Charge		7.5	nC	V _{GS} = 10 V, I _D = 2.0 A V _{DD} = 200 V	

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Electrical Characteristics (Cont.) (T_C = 25°C unless otherwise noted)

Symbol	Characteristic	Тур	Max	Unit	Test Conditions
Source-Dra	in Diode Characteristics				
V _{SD}	Diode Forward Voltage				
	IRF710/711		1.6	٧	I _S = 1.5 A; V _{GS} = 0 V
	IRF712/713		1.5	V	I _S = 1.3 A; V _{GS} = 0 V
t _{rr}	Reverse Recovery Time	380		ns	$I_S = 1.5 \text{ A}; dI_S/dt = 25 \text{ A}/\mu S$

Notes

Notes $1. \ T_J = +25^{\circ}\text{C to } +150^{\circ}\text{C}$ 2. Pulse test: Pulse width $\leq 80~\mu\text{s}$, Duty cycle $\leq 1\%$ 3. Switching time measurements performed on LEM TR-58 test equipment.

Typical Performance Curves

Figure 1 Output Characteristics

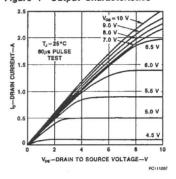


Figure 3 Transfer Characteristics

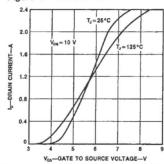


Figure 2 Static Drain to Source Resistance vs Drain Current

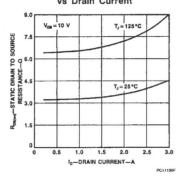


Figure 4 Temperature Variation of Gate to Source Threshold Voltage

